<table>
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<th>SIZE</th>
<th>SCALE</th>
<th>DWG.NO.</th>
<th>REV.</th>
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**Board Characteristics: 16-Layer Board**

- All dimensions are inches unless specified otherwise.
- Material: FR4, Tg > 170 C.
- Board Thickness: 0.095 plus/minus 0.008 inches.
- Minimum Trace Width: 0.005 inches.
- Silkscreen on Both Sides.
- Board Thickness: 0.095 plus/minus 0.008 inches.
- Minimum Trace Width: 0.005 inches.
- Electroless Nickel/Immersion Gold plating; apply solder mask.
- 1 oz Copper for top, bottom and power layers; 1/2 oz Copper for embedded signal layers.
- Minimum clearance: 0.004 inches on all signal layers.
- All dimensions in inches unless specified otherwise.

**Board's Hole Schedule**

- Diameter of drilled hole: 0.7mm plus/minus 0.02mm (in mils).
- Width of milled areas: 0.1 inches plus/minus 0.05 inches.
- Mill the top and bottom of board on the slider side to a thickness of 0.063 plus/minus 0.008 inches.
- Diameter of finished plated through hole: 0.6mm plus/minus 0.05mm.
- Hole Filing: min 25um Cu, 2.5-5um Ni, 0.05-0.2um Au (Electroless Ni/Immersion Au).
- Minimum clearance: 0.004 inches on all signal layers.
- All dimensions in inches unless specified otherwise.

**Notes**

1. Diameter of drilled hole: 0.7mm plus/minus 0.02mm (in mils).
2. Width of milled areas: 0.1 inches plus/minus 0.05 inches.
3. Mill the top and bottom of board on the slider side to a thickness of 0.063 plus/minus 0.008 inches.
4. Diameter of finished plated through hole: 0.6mm plus/minus 0.05mm.
5. Hole Filing: min 25um Cu, 2.5-5um Ni, 0.05-0.2um Au (Electroless Ni/Immersion Au).
6. Minimum clearance: 0.004 inches on all signal layers.
7. Impedance 50 Ohm for all 5-mil traces.
8. FHS tolerances: plus/minus 0.003 inches unless specified otherwise.
10. This is a pressfit tech. thru hole with the following specs:
    - Diameter of drilled hole: 0.7mm plus/minus 0.02mm (in mils).
    - Diameter of finished plated through hole: 0.6mm plus/minus 0.05mm.
    - Hole Filing: min 25um Cu, 2.5-5um Ni, 0.05-0.2um Au (Electroless Ni/Immersion Au).
11. 45 degree chamfer min 25um Cu, 2.5-5um Ni, 0.05-0.2um Au (Electroless Ni/Immersion Au).
12. Minimum clearance: 0.004 inches on all signal layers.
13. All dimensions in inches unless specified otherwise.
14. Material: FR4, Tg > 170 C.
15. Board Thickness: 0.095 plus/minus 0.008 inches.
16. Minimum Trace Width: 0.005 inches.
17. Silkscreen on Both Sides.
18. Board Thickness: 0.095 plus/minus 0.008 inches.
19. Minimum Trace Width: 0.005 inches.
20. Electroless Nickel/Immersion Gold plating; apply solder mask.
21. 1 oz Copper for top, bottom and power layers; 1/2 oz Copper for embedded signal layers.
22. Minimum clearance: 0.004 inches on all signal layers.
23. All dimensions in inches unless specified otherwise.